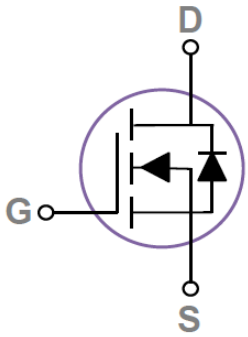
General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

DFN5X6 Pin Configuration



BVDSS	RDSON	ID
65V	5.6mΩ	83A

Features

◆65V,83A, RDS(ON) =5.6mΩ @VGS = 10V
◆Improved dv/dt capability
◆Fast switching
◆100% EAS Guaranteed
◆Green Device Available

Application

◆Networking
◆Load Switch
◆LED applications
◆Quick Charger

Ordering / Marking Information

ECP6982X XX X

Package：
F2：DFN5*6

Taping：
R：Tape and Reel

Part Namber	Marking	Marking Information
ECP6982XF2R	6982X LLLLL YYWW	LLLLL：Lot No YYWW：Date Code

Absolute Maximum Ratings Tc=25℃ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	65	V
V_{GS}	Gate-Source Voltage	±20/-12	V
I_D	Drain Current – Continuous (T_C=25℃)	83	A
	Drain Current – Continuous (T_C=100℃)	52	A
I_{DM}	Drain Current – Pulsed[1]	332	A
EAS	Single Pulse Avalanche Energy[2]	140	mJ
IAS	Single Pulse Avalanched Current[2]	53	A
P_D	Power Dissipation (T_C=25℃)	96	W
	Power Dissipation – Derate above 25℃	0.77	W/℃
T_{STG}	Storage Temperature Range	-50 to 150	℃
T_J	Operating Junction Temperature Range	-50 to 150	℃

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	℃/W
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	1.3	℃/W

Electrical Characteristics T_J=25 ℃, unless otherwise noted

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V , I_D=250uA	65	---	---	V
$\triangle BV_{DSS}/\triangle T_J$	BV_{DSS} Temperature Coefficient	Reference to 25℃ , I_D=1mA	---	0.03	---	V/℃
I_{DSS}	Drain-Source Leakage Current	V_{DS}=60V , V_{GS}=0V , T_J=25℃	---	---	1	uA
		V_{DS}=48V , V_{GS}=0V , T_J=85℃	---	---	10	uA
I_{GSS}	Gate-Source Leakage Current	V_{GS}=20V , V_{DS}=0V	---	---	100	nA

On Characteristics

$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=10V , I_D=20A	---	4.6	5.6	mΩ
		V_{GS}=4.5V , I_D=15A	---	8.2	10.5	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS}=V_{DS} , I_D =250uA	1	1.6	2.5	V
$\triangle V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	-5.5	---	mV/℃
gfs	Forward Transconductance	V_{DS}=10V , I_D=3A	---	10	---	S

Dynamic and switching Characteristics

Q_g	Total Gate Charge[3,4]	V_{DS}=30V, V_{GS}=10V, I_D=15A	---	34.7	70	nC
Q_{gs}	Gate-Source Charge[3,4]		---	4.9	10	
Q_{gd}	Gate-Drain Charge[3,4]		---	11.1	22	
$T_{d(on)}$	Turn-On Delay Time[3,4]	V_{DD}=30V, V_{GS}=10V , R_G=6Ω I_D=1A	---	10.2	21	ns
T_r	Rise Time[3,4]		---	16	32	
$T_{d(off)}$	Turn-Off Delay Time[3,4]		---	42	84	
T_f	Fall Time[3,4]		---	38	76	
C_{iss}	Input Capacitance	V_{DS}=30V, V_{GS}=0V , F=1MHz	---	1910	3800	pF
C_{oss}	Output Capacitance		---	520	1040	
C_{rss}	Reverse Transfer Capacitance		---	30	60	
R_g	Gate resistance	V_{GS}=0V, V_{DS}=0V, F=1MHz	---	1.2	---	Ω

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current	V_G=V_D=0V , Force Current	---	---	83	A
I_{SM}	Pulsed Source Current		---	---	166	A
V_{SD}	Diode Forward Voltage	V_{GS}=0V , I_S=1A , T_J=25℃	---	---	1	V
T_{rr}	Reverse Recovery Time	V_{GS}=10V,I_S=10A , di/dt=100A/μs T_J=25℃	---	48.4	---	ns
Q_{rr}	Reverse Recovery Charge		---	54.2	---	nC

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. V_{DD}=25V,V_{GS}=10V,L=0.1mH,I_{AS}=53A.,R_G=25Ω,Starting T_J=25℃.
3. The data tested by pulsed , pulse width ≦ 300us , duty cycle ≦ 2%.
4. Essentially independent of operating temperature.

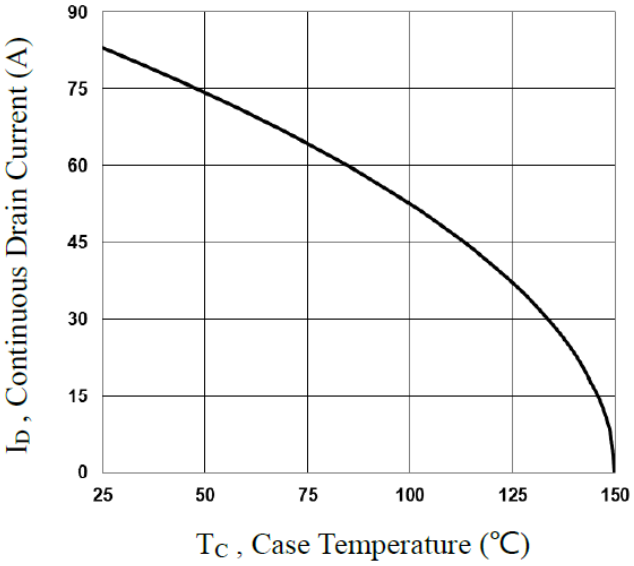


Fig.1 Continuous Drain Current vs. T_C

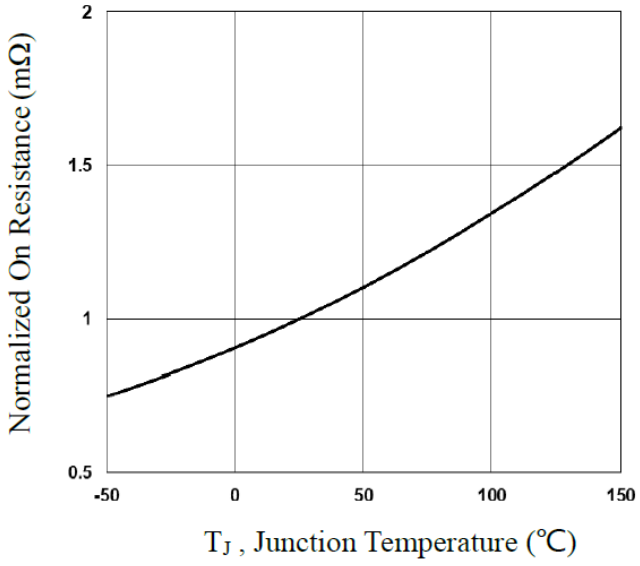


Fig.2 Normalized RDSON vs. T_J

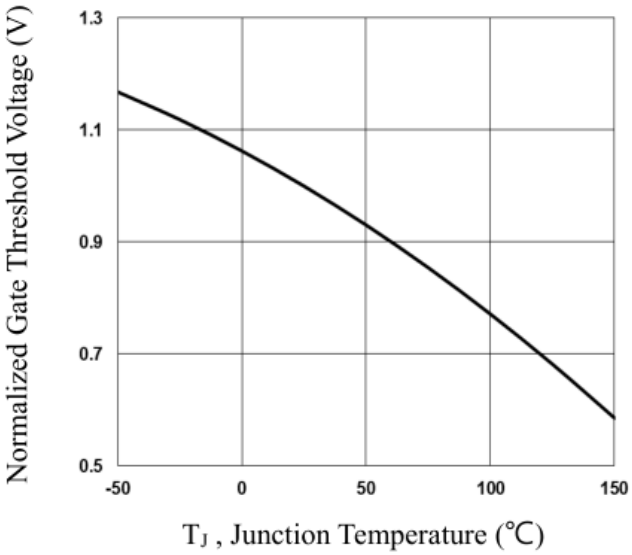


Fig.3 Normalized Vth vs. T_J

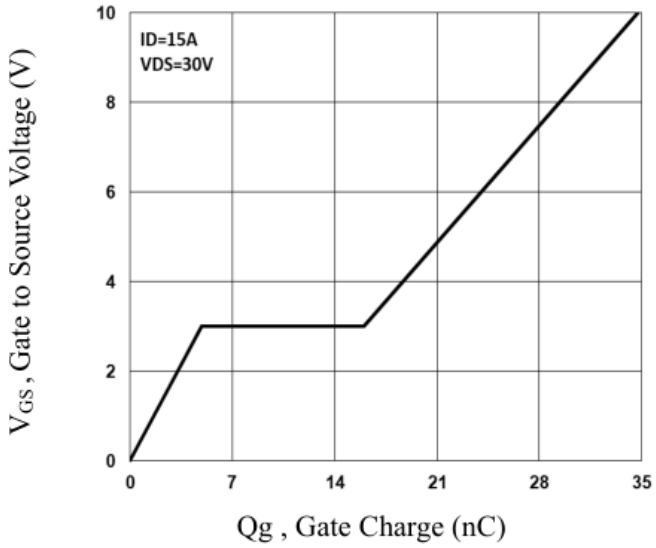


Fig.4 Gate Charge Characteristics

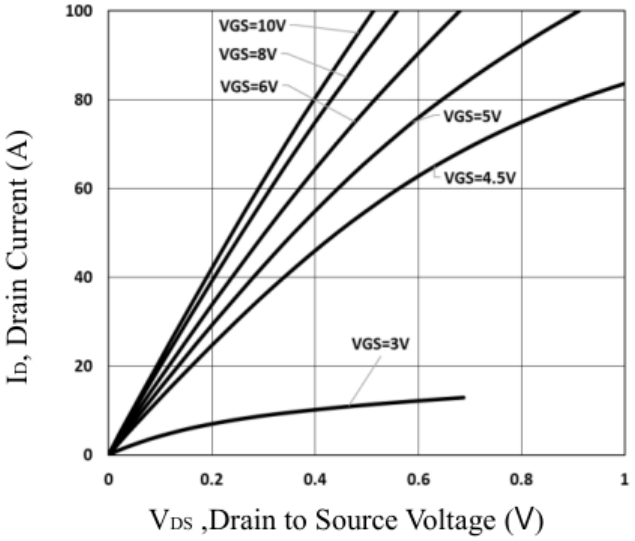


Fig.5 Typical Output Characteristics

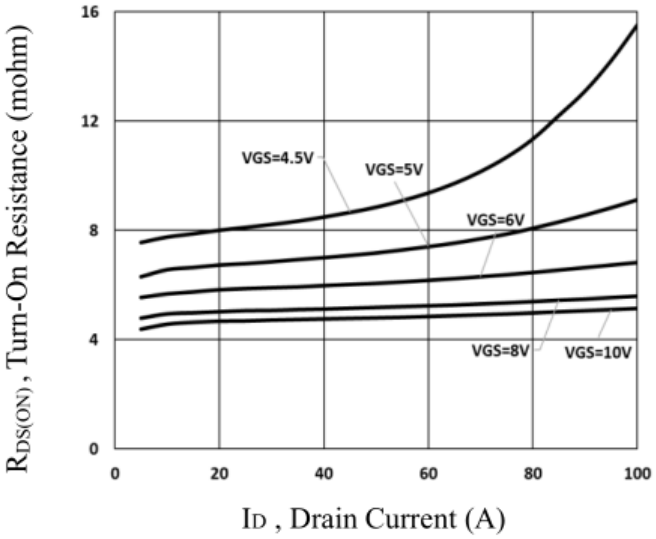


Fig.6 Turn-On Resistance vs. ID

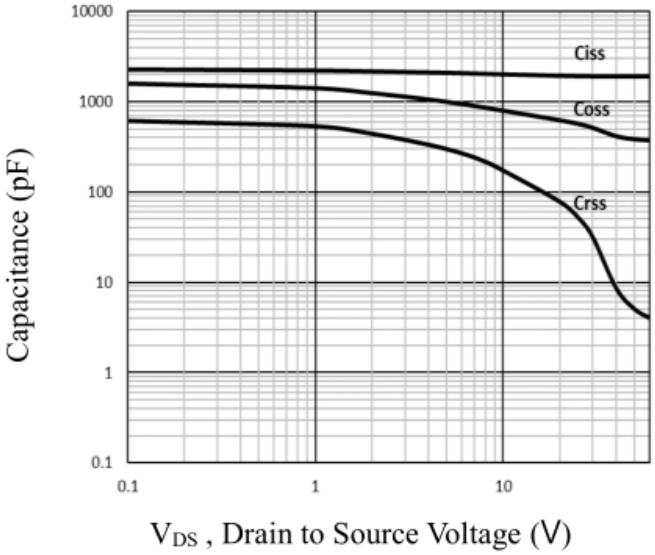


Fig.7 Capacitance Characteristics

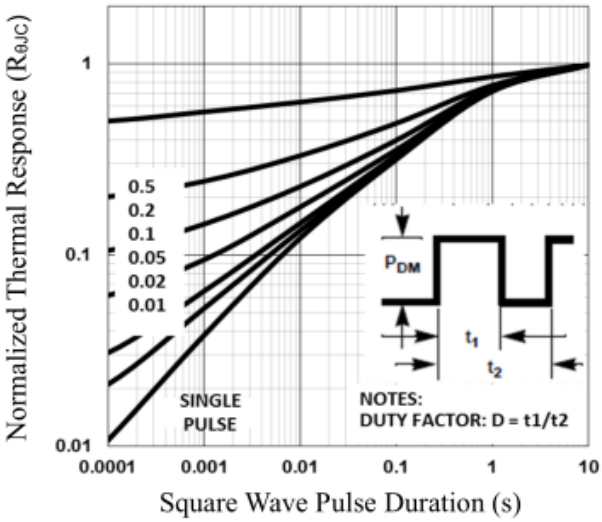


Fig.8 Normalized Transient Impedance

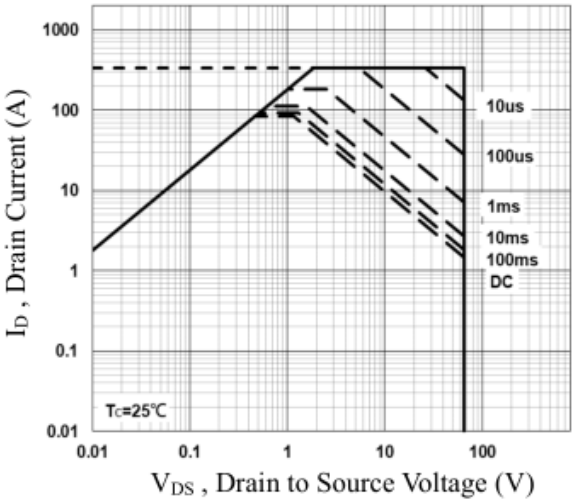


Fig.9 Maximum Safe Operation Area

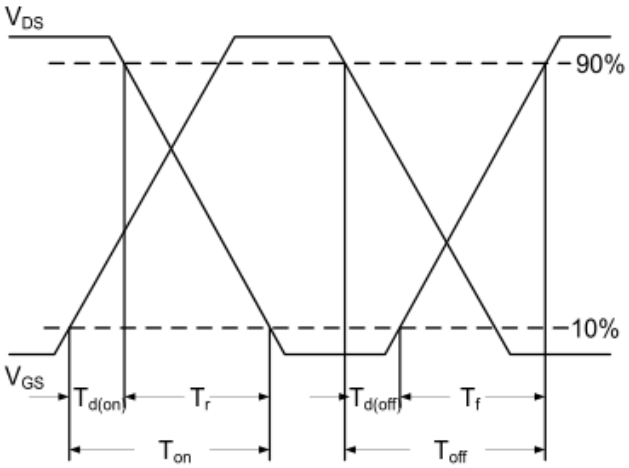


Fig.10 Switching Time Waveform

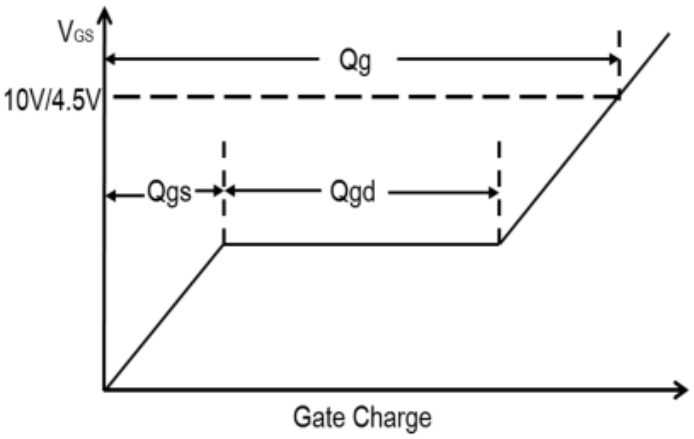
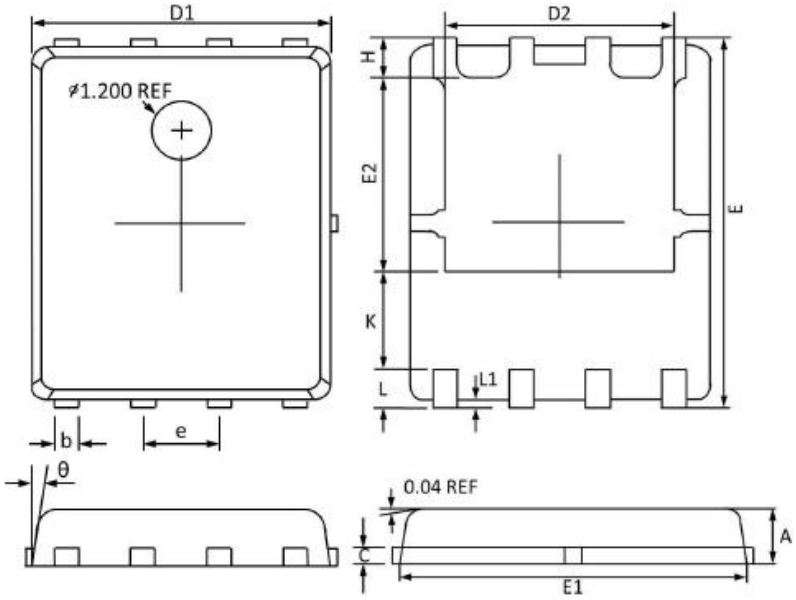


Fig.11 Gate Charge Waveform

DFN5*6 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	1.100	0.800	0.043	0.031
b	0.510	0.330	0.020	0.013
C	0.300	0.200	0.012	0.008
D1	5.100	4.800	0.201	0.189
D2	4.100	3.610	0.161	0.142
E	6.200	5.900	0.244	0.232
E1	5.900	5.700	0.232	0.224
E2	3.780	3.350	0.149	0.132
e	1.27BSC		0.05BSC	
H	0.700	0.410	0.028	0.016
K	1.500	1.100	0.059	0.043
L	0.710	0.510	0.028	0.020
L1	0.200	0.060	0.008	0.002
θ	12°	0°	12°	0°